



Material Content Data Sheet



Sales Product Name		BCX 68-10 H6327		Issued		1. August 2018		
MA#		MA001219988						
Package		PG-SOT89-4-3		Weight*		53.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.007	0.01		130	
	noble metal	gold	7440-57-5	0.027	0.05		502	
	inorganic material	silicon	7440-21-3	0.326	0.61	0.67	6132	6764
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		474	
	non noble metal	chromium	7440-47-3	0.076	0.14		1422	
	non noble metal	copper	7440-50-8	25.112	47.20	47.40	472050	474041
wire	non noble metal	copper	7440-50-8	0.048	0.09	0.09	905	905
encapsulation	organic material	carbon black	1333-86-4	0.267	0.50		5018	
	plastics	epoxy resin	-	4.004	7.53		75277	
	inorganic material	silicondioxide	60676-86-0	22.425	42.16	50.19	421550	501845
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15063	15063
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1382	1382
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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